



# Taiwan 3DS-IC Committee Meeting Summary and Minutes

Taiwan 3DS-IC TC Meeting Dec 21. 2012,10:00-12:00 SEMI Taiwan, HsinChu

#### **Next Committee Meeting**

March 14, 2013

3DS-IC TC Meeting, ITRI, HsinChu

#### **Committee Announcements (optional)**

Table 1 Meeting Attendees: Co-Chairs: Dr. YS Lai (ASE) SEMI Staff: Catherine Chang

DEMI Suit. Cutionic Chang					
Company	Last	First	Company	Last	First
KYEC	Chen	Wendy	SEMATECH	Yang	Terry
ITRI	Ku	TK	ITRI	Ku	TK
GUEC	Liu	Guan Jiun	NTUST	Chen	Chao- Chang
KYEC	Ko	Sam	SPIL	Chiu	Chi Hsin
CMPUG TW	Kong	LC			
ITRI	Chen	Erh-Hao			
ASE	Lai	Yi-Shao			
ITRI	Yao	Bin-Cheng			

### Table 2 Leadership Changes: None

### Table 3 Ballot Results (or move to Section 4, Ballot Review)

Passed ballots and line items will be submitted to the ISC Audit & Review Subcommittee for procedural review.

Failed ballots and line items were returned to the originating task forces for re-work and re-balloting.

None

#### Table 4 Authorized Ballots (or move to Section 7, New Business)

Doc 5474 approval cycle 2, 2013 ballot.

#	When	SC/TF/WG	Details
5474		Middle end process TF	Approval by TC for cycle 2, 2013 ballot

## Table 5 Authorized Activities (or move to Section 7, New Business)

Note: SNARFs and TFOFs are available for review on the SEMI Web site at: <a href="http://downloads.semi.org/web/wstdsbal.nsf/TFOFSNARF">http://downloads.semi.org/web/wstdsbal.nsf/TFOFSNARF</a>





Table 6 New Action Items (or move to Section 8, Action Item Review)

None

Table 7 Previous Meeting Actions Items (or move to Section 8, Action item Review)

None

#### 1 Welcome, Reminders, and Introductions

Dr. YS Lai called the meeting to order at 10:00. The meeting reminders on antitrust issues, intellectual property issues and holding meetings with international attendance were reviewed. Attendees introduced themselves.

Attachment: Required Elements 2012

#### 2 Review of Previous Meeting Minutes

The committee reviewed the minutes of the previous meeting.

Attachment: 3DS-IC Meeting Minutes 20120906

## 3. Staff Report

North America Standards Spring 2013 Meetings

April 1-4

SEMI Headquarters 3081 Zanker Road San Jose, California / U.S.A.

Tuesday, April 2

Inspection & Metrology TF (8:00 AM to 10:00 AM)

Bonded Wafer Stacks TF (10:00 AM to 12:00 Noon)

Thin Wafer Handling TF (1:00 PM to 3:00 PM)

NA 3DS-IC Committee (3:00 PM to 5:00 PM)

#### 4 Liaison Reports

4.1 Dr. YS Lai Report: -- NA Liaison Report

• New SANRF from Inspection & Metrology TF

New Standard: Test Method for Measuring Warp, Bow and TTV on Silicon and Glass Wafers Mounted on Wire Grids by Automated Non-Contact Scanning using Laser Scanning Interferometry

Upcoming NA 3DS-IC Ballots

*Voting	Period – Cycle 1, 2013 *	
Doc#	Document Title	Task Force
5173C	New Standard: Guide for Describing Materials Properties for a 300 mm 3DS-IC Wafer Stack	Bonded Wafer Stacks TF





5410	New Standard: Guide for Metrology Techniques to be Used in Measurement of Geometrical Parameters of Through-Silicon Vias (TSVs) in 3DS-IC Structures	Inspection & Metrology TF
5175	New Standard: Guide for Multi-Wafer Transport and Storage Containers for 300 mm, Thin Silicon Wafers on Tape Frames	Thin Wafer Handling

Attachment: NA 3DS-IC report December 2012





## 5 Ballot Review

None

- 6 Old Business
- 7 New Business
- 8 Action Item Review
- 8.1 Open Action Items :None
- 8.2 New Action Items
- 9 Next Meeting and Adjournment

March 14, 2013





Respectfully submitted by: Catherine Chang Sr. Manager SEMI Taiwan

Phone: 03-573 3399 # 217 Email: cchang@semi.org

Minutes approved by:

TK Ku/ITRI, Co-Chair	<date approved=""> 6 June, 2012</date>
----------------------	--

# Table 8 Index of Available Attachments #1

#	Title	#	Title
1	Required Elements 2011		
2	3DS-IC Meeting Minutes 20120209		
3	NA 3DS-IC report April 2012		
	SNARF_Middle-end process Doc.2		
	SNARF_Middle-end process		

<sup>#1</sup> Due to file size and delivery issues, attachments must be downloaded separately. A .zip file containing all attachments for these minutes is available at www.semi.org. For additional information or to obtain individual attachments, please contact [SEMI Staff Name] at the contact information above.